

L Number	Hits	Search Text	DB	Time stamp
	0	156/\$.ccls. and (anisotropical near1 tape) and (cut or "cut-off") and conductive	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/01 14:19
	0	156/\$.ccls. and (anisotropical near1 tape) and conductive	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/30 14:00
	0	156/\$.ccls. and (anisotropical near2 tape) and conductive	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/30 14:00
	0	156/\$.ccls. and (anisotropical near3 tape) and conductive	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/30 20:19
	0	156/\$.ccls. and (anisotropical near3 tape)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/02 11:48
	17	156/\$.ccls. and (anisotropic near3 tape)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/30 14:12
	0	83/\$.ccls. and (anisotropic near3 tape)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/30 19:30
	22	29/\$.ccls. and (anisotropic near3 tape)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/30 14:24
	375	(156/353).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/02 11:24
	418	(156/359).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/01 14:11
	210	(156/360).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/30 17:42
	1	matsushita.asn. and (anisotropical near3 tape) and conductive	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/30 16:55

	51	matsushita.asn. and (anisotropic near3 tape) and conductive	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/02 10:58
	617	(156/378).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/01 14:06
	169	(156/379).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/30 19:01
	0	83/\$.ccls. and (TCP) and (cut or "cut-off") and (measure or measurement)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/30 19:31
	2401	83/\$.ccls. and (cut or "cut-off") and (measure or measurement)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/30 19:31
	157	83/\$.ccls. and (cut or "cut-off") and (measure or measurement) and (tape or film) and (circuit or electrode)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/30 20:16
	0	(anisotropical near3 tape) and conductive and (cut or "cut-off") and (measure or measurement)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/30 20:19
	26	(anisotropic near3 tape) and conductive and (cut or "cut-off") and (measure or measurement)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/30 20:31
	301	(TCP) and conductive and (cut or "cut-off") and (measure or measurement)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/30 20:32
	153	(TCP) and conductive and (cut or "cut-off") and (measure or measurement) and (adhesive)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/30 20:32
	0	83/\$.ccls. and (TCP or "tape carrier package") and ((temperature or thermal) near2 (compensation or comparation or measurement))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/30 20:54
	6	156/\$.ccls. and (TCP or "tape carrier package") and ((temperature or thermal) near2 (compensation or comparation or measurement))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/30 21:01
	1	29/\$.ccls. and (TCP or "tape carrier package") and ((temperature or thermal) near2 (compensation or comparation or measurement))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/30 20:54

	79	(118/677).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/01 14:47
	634	(156/521).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/01 15:52
	0	156/\$.ccls. and (semiconductor same tape) and (temperature near4 compensation)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/01 14:56
	183	(156/367).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/01 14:48
	0	156/\$.ccls. and (semiconductor same tape) and (size near4 compensation)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/01 14:55
	0	156/\$.ccls. and (semiconductor same tape) and (size near4 correction)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/01 14:55
	0	156/\$.ccls. and (semiconductor same tape) and (temperature same compensation)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/01 14:56
	0	156/\$.ccls. and (semiconductor near20 tape) and (temperature near20 compensation)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/01 14:56
	0	83/\$.ccls. and (semiconductor near20 tape) and (temperature near20 compensation)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/01 14:56
	1	29/\$.ccls. and (semiconductor near20 tape) and (temperature near20 compensation)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/01 15:08
	0	29/\$.ccls. and (TCP or "tape carrier package") and (temperature near20 compensation)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/01 16:04
	44	29/\$.ccls. and (adhesive) and (temperature near20 compensation)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/01 15:29
	22	156/\$.ccls. and (adhesive) and (temperature near20 compensation) and (tape or film)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/01 15:30

	203	(29/835).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/01 16:05
	24	29/\$.ccls. and (TAB or (tape and attach\$5 and bond\$4)) and (temperature near20 compensation)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/01 16:06
	10	156/\$.ccls. and (TAB or (tape and attach\$5 and bond\$4)) and (temperature near20 compensation)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/01 16:19
	1	83/\$.ccls. and (TAB or (tape and attach\$5 and bond\$4)) and (temperature near20 compensation)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/01 16:07
	393	(29/833).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/01 18:17
	1	156/\$.ccls. and (TAB or (tape and attach\$5 and bond\$4)) and (deformation near20 compensation)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/02 10:17
	0	83/\$.ccls. and (TAB or (tape and attach\$5 and bond\$4)) and (deformation near20 compensation)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/01 16:20
	1	29/\$.ccls. and (TAB or (tape and attach\$5 and bond\$4)) and (deformation near20 compensation)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/01 16:20
	120	matsushita.asn. and (ACF)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/02 10:56
	87	(83/75.5).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/01 18:18
	65	(83/76.4).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/01 18:20
	298	(83/364).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/01 18:20
	0	118/\$.ccls. and (adhesive near3 dispense\$4) and (deformation near20 compensation)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/02 10:45

	0	118/\$.ccls. and (adhesive near3 dispense\$4) and (size near20 comparation)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/02 10:46
	1	118/\$.ccls. and (adhesive near3 dispense\$4) and (size near20 compensation)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/02 10:45
	0	118/\$.ccls. and (adhesive near3 dispense\$4) and (size near20 comparision)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/02 11:47
	9	fuji.asn. and (ACF)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/02 10:56
	3	fuji.asn. and (anisotropic near3 tape) and conductive	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/02 11:22
	52	(700/303).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/02 11:27
	180	(700/302).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/02 11:48
	0	700/\$.ccls. and (adhesive near3 dispense\$4) and (size near20 comparision)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/02 14:39
	0	702/\$.ccls. and (adhesive near3 dispense\$4) and (size near20 comparision)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/02 14:40
	0	700/\$.ccls. and (anisotropical near3 tape)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/02 11:48
	97	(702/97).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/02 11:58
	327	(702/158).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/02 12:18
	102	(702/101).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/02 12:18

-	18	118/\$.ccls. and ciardella 700/\$.ccls. and (adhesive near3 dispense\$4) and (size near20 comparison)	USPAT USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/02 14:26
-	0	702/\$.ccls. and (adhesive near3 dispense\$4) and (size near20 comparison)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/02 14:40
-	6	700/\$.ccls. and (adhesive near3 dispense\$4) and (size near20 control)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/02 14:41
-	3	702/\$.ccls. and (adhesive near3 dispense\$4) and (size near20 control)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/02 14:42
-	4	702/\$.ccls. and (adhesive near3 dispense\$4) and (location near20 control)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/02 14:42
-	9	700/\$.ccls. and (adhesive near3 dispense\$4) and (location near20 control)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/02 14:43
-	28	118/\$.ccls. and (adhesive near3 dispense\$4) and (location near20 control)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/02 18:43
-	40	156/\$.ccls. and (adhesive near3 dispense\$4) and (location near20 control)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/02 14:45
-	0	118/\$.ccls. and (resin near3 dispense\$4) and (location near20 weight)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/02 18:43
-	0	118/\$.ccls. and (ACF near3 dispense\$4) and (location near20 weight)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/02 18:43
-	6	118/\$.ccls. and (adhesive near3 dispense\$4) and (location near20 weight)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/02 18:45
-	0	118/\$.ccls. and (adhesive near3 dispense\$4) and (location near20 mass)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/02 19:33

-	0	118/\$.ccls. and (adhesive near3 dispense\$4) and (leadframe)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/02 19:33
-	18	118/\$.ccls. and (leadframe)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/02 19:36
-	79	156/\$.ccls. and (leadframe)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/02 19:36

L Number	Hits	Search Text	DB	Time stamp
15	1177	(156/64).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/03 11:49
16	354	(156/358).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/03 11:49
17	183	(156/367).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/03 11:49
18	95	(156/368).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/03 11:49
30	807	(156/361).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/03 11:50
32	617	(156/378).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/03 11:50
39	1	("5564183").PN.	USPAT	2004/05/03 11:50
19	169	(156/379).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/03 11:50
20	8	(((156/64).CCLS.) ((156/353).CCLS.) ((156/358).CCLS.) ((156/359).CCLS.) ((156/360).CCLS.) ((156/361).CCLS.) ((156/367).CCLS.) ((156/368).CCLS.) ((156/378).CCLS.) ((156/379).CCLS.)) and ((circuit or chip or semiconductor or die or electrode) same (bond or weld or attach or attachment)) and ((temperature or heat or thermal) same (correlation or correction or calibration))	USPAT	2004/05/03 11:50
21	4	(((156/64).CCLS.) ((156/353).CCLS.) ((156/358).CCLS.) ((156/359).CCLS.) ((156/360).CCLS.) ((156/361).CCLS.) ((156/367).CCLS.) ((156/368).CCLS.) ((156/378).CCLS.) ((156/379).CCLS.)) and ((circuit or chip or semiconductor or die or electrode) same (bond or weld or attach or attachment)) and ((temperature or heat or thermal) same (correlation or correction or calibration))	US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/03 11:50
22	59	(29/.ccls.) and ((circuit or chip or semiconductor or die or electrode) same (bond or weld or attach or attachment)) and ((temperature or heat or thermal) same (correlation or correction or calibration))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/03 11:50
23	41	(156/.ccls.) and ((circuit or chip or semiconductor or die or electrode) same (bond or weld or attach or attachment)) and ((temperature or heat or thermal) same (correlation or correction or calibration))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/03 11:50

24	72	((438/.ccls.) and ((circuit or chip or semiconductor or die or electrode) same (bond or weld or attach or attachment)) and ((temperature or heat or thermal) same (correlation or correction or calibration)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/03 11:50
25	30	((700/.ccls.) and ((circuit or chip or semiconductor or die or electrode) same (bond or weld or attach or attachment)) and ((temperature or heat or thermal) same (correlation or correction or calibration)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/03 11:50
26	58	((702/.ccls.) and ((circuit or chip or semiconductor or die or electrode) same (bond or weld or attach or attachment)) and ((temperature or heat or thermal) same (correlation or correction or calibration)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/03 11:50
27	375	(156/353).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/03 11:51
28	418	(156/359).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/03 11:51
29	210	(156/360).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/03 11:51
31	5	(((156/361).CCLS.)) and ((circuit or chip or semiconductor or die or electrode) and ((temperature or heat or thermal) same (correlation or correction or calibration)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/03 11:51
33	9	(((156/378).CCLS.)) and ((circuit or chip or semiconductor or die or electrode) and ((temperature or heat or thermal) same (correlation or correction or calibration)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/03 11:51
34	66	((29/.ccls.) and ((circuit or chip or semiconductor or die or electrode) same (bond or weld or attach or attachment)) and ((temperature or heat or thermal) same (compensation)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/03 11:51
35	18	((156/.ccls.) and ((circuit or chip or semiconductor or die or electrode) same (bond or weld or attach or attachment)) and ((temperature or heat or thermal) same (compensation)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/03 11:51
36	118	((438/.ccls.) and ((circuit or chip or semiconductor or die or electrode) same (bond or weld or attach or attachment)) and ((temperature or heat or thermal) same (compensation)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/03 11:51
37	11	((700/.ccls.) and ((circuit or chip or semiconductor or die or electrode) same (bond or weld or attach or attachment)) and ((temperature or heat or thermal) same (compensation)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/03 11:51
38	21	((702/.ccls.) and ((circuit or chip or semiconductor or die or electrode) same (bond or weld or attach or attachment)) and ((temperature or heat or thermal) same (compensation)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/03 11:51

40	11	"5564183"	USPAT	2004/05/03 11:51
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